



SPARC – Sensor Pixel Asynchronous Readout CMOS

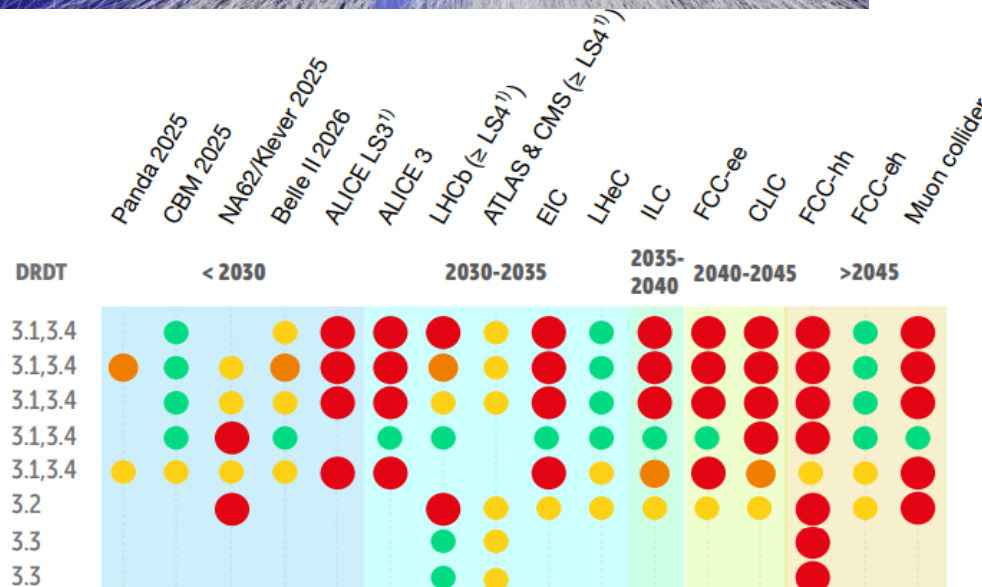
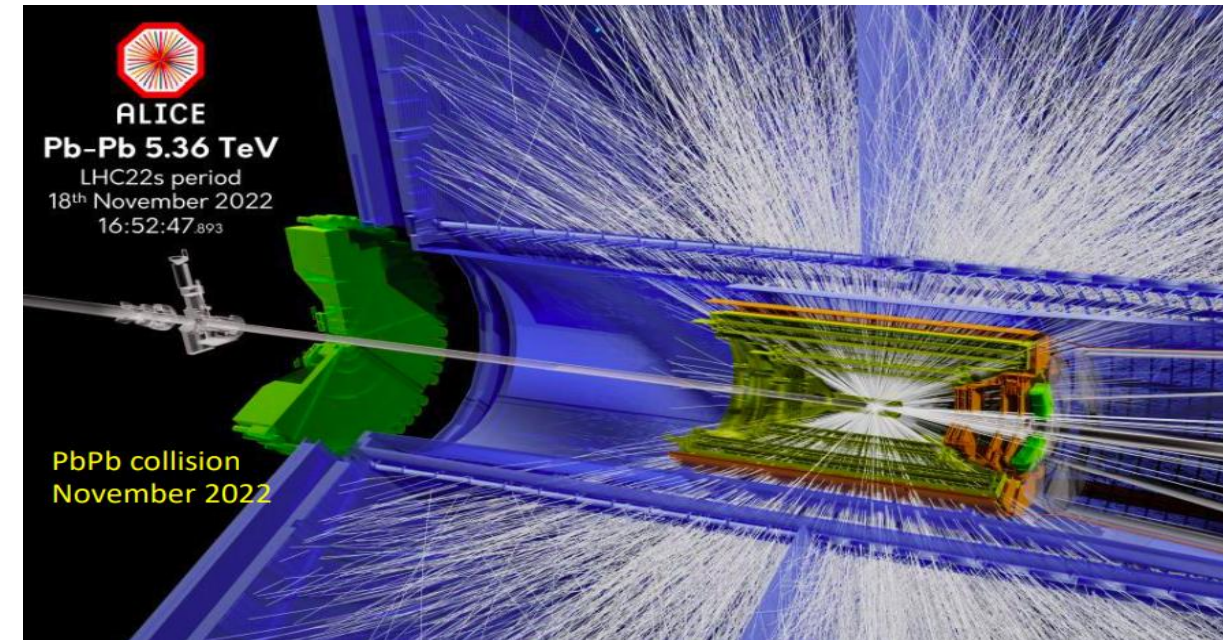


Camille Fournier on the behalf of SPARC core team

Phd student, Institut Pluridisciplinaire Hubert Curien (IPHC)

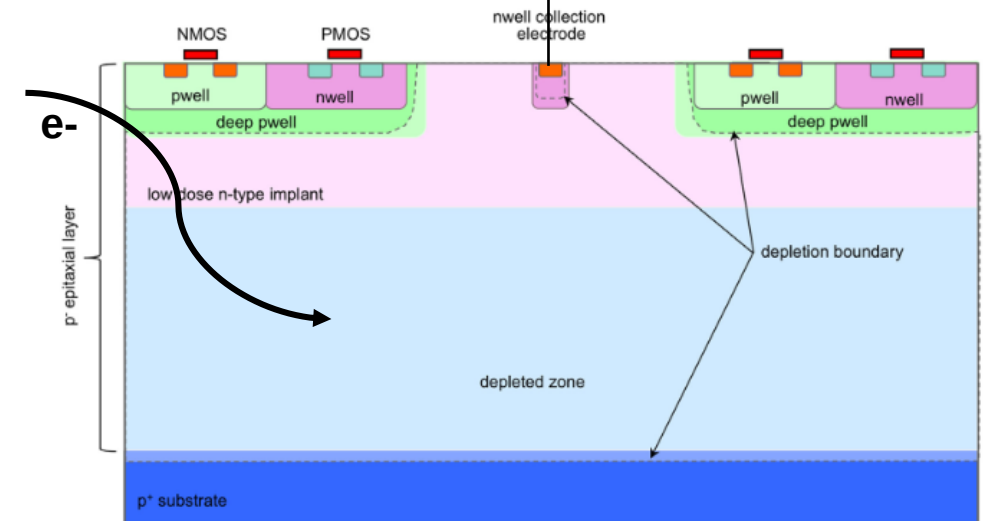
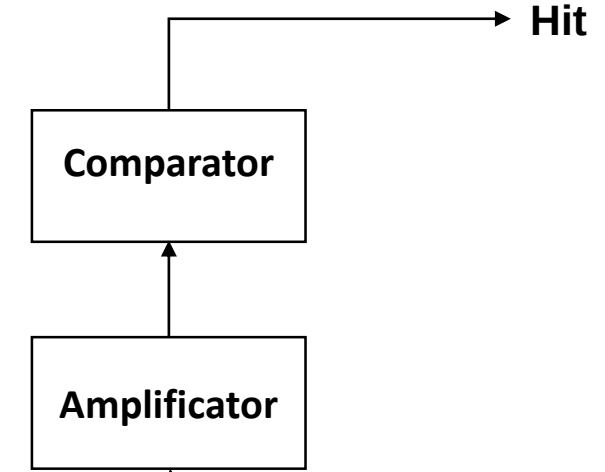
Subatomic Research Department, C4PI team

Context



MAPS : Monolithic Active Pixel Sensors

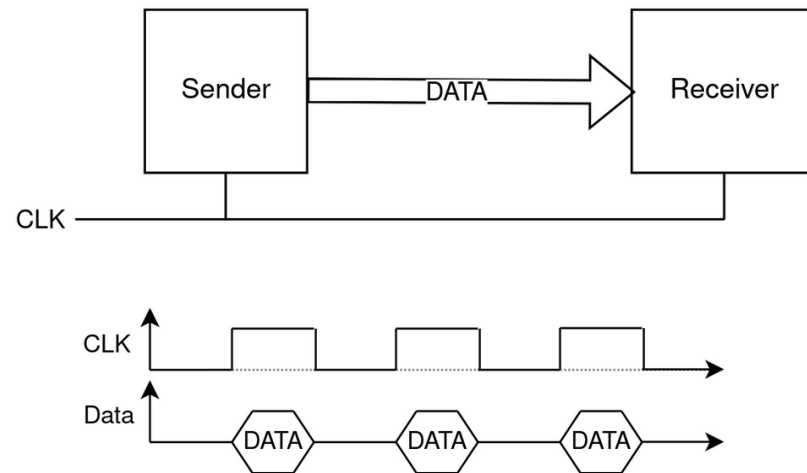
- Detection and readout on the same chip
- retrieve the exact hit coordinates within the pixel matrix
- Established in the CERN ALICE ITS2 experiment since 2021 (ALPIDE sensors)



Asynchronous readout reminders

Synchronous

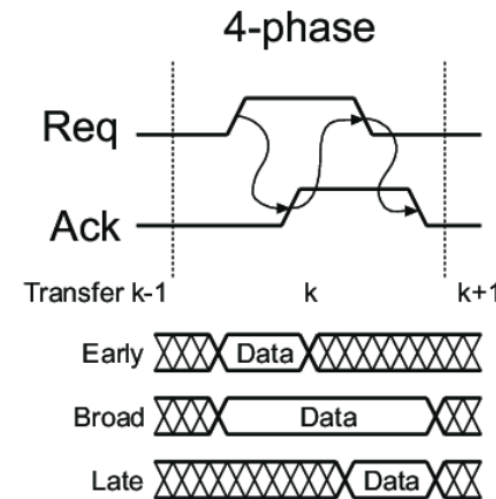
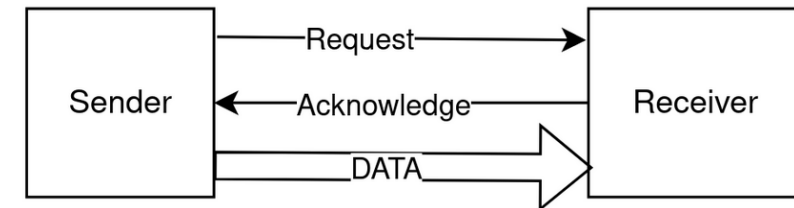
Data are read at regular intervals, synchronized to a common clock running at a specific frequency



- (-) Continuous readout (Wastes bandwidth)
- (-) Sensitive to synchronization issues
- (-) Complex clock distribution (increases latency)

Asynchronous

Data are read immediately when they become available through a handshake protocol



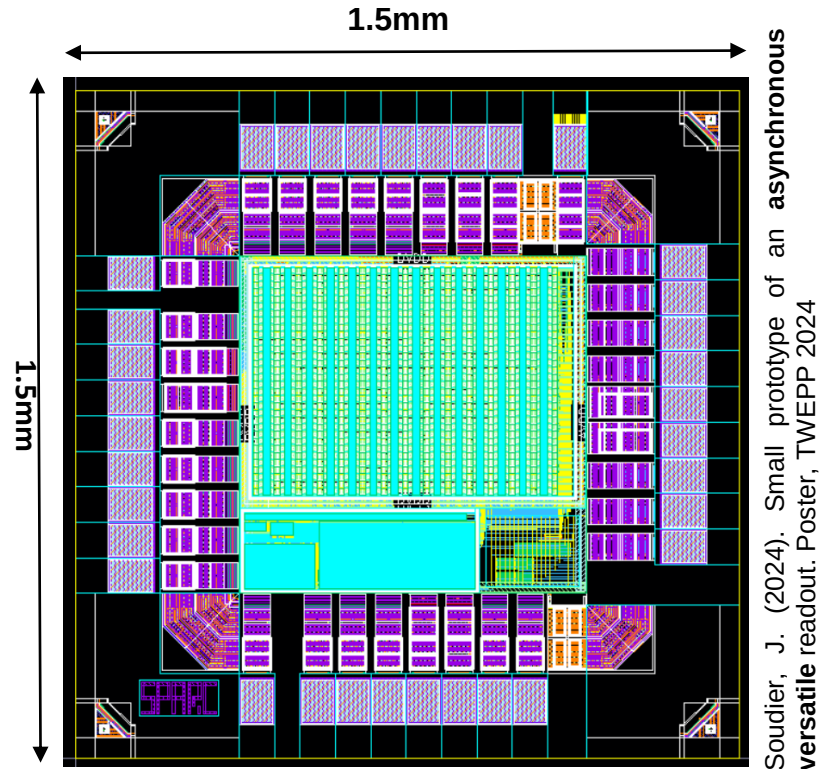
S = sender
R = receiver

1. S issues data and sets Req high
2. R absorbs the data and sets ack high
3. S respond by taking Req low
4. R put Ack low

(+) Data-driven readout

Carlsson, J., Palmkvist, K., & Wanhammar, L. (2003). An 8-by-8 point 2D DCT processor based on the GALS approach. In IEEE NorChip Conference

SPARC – Sensor Pixel Asynchronous Readout CMOS



*Layout of SPARC 1.5x1.5 mm
build in a TPSCo 65nm*

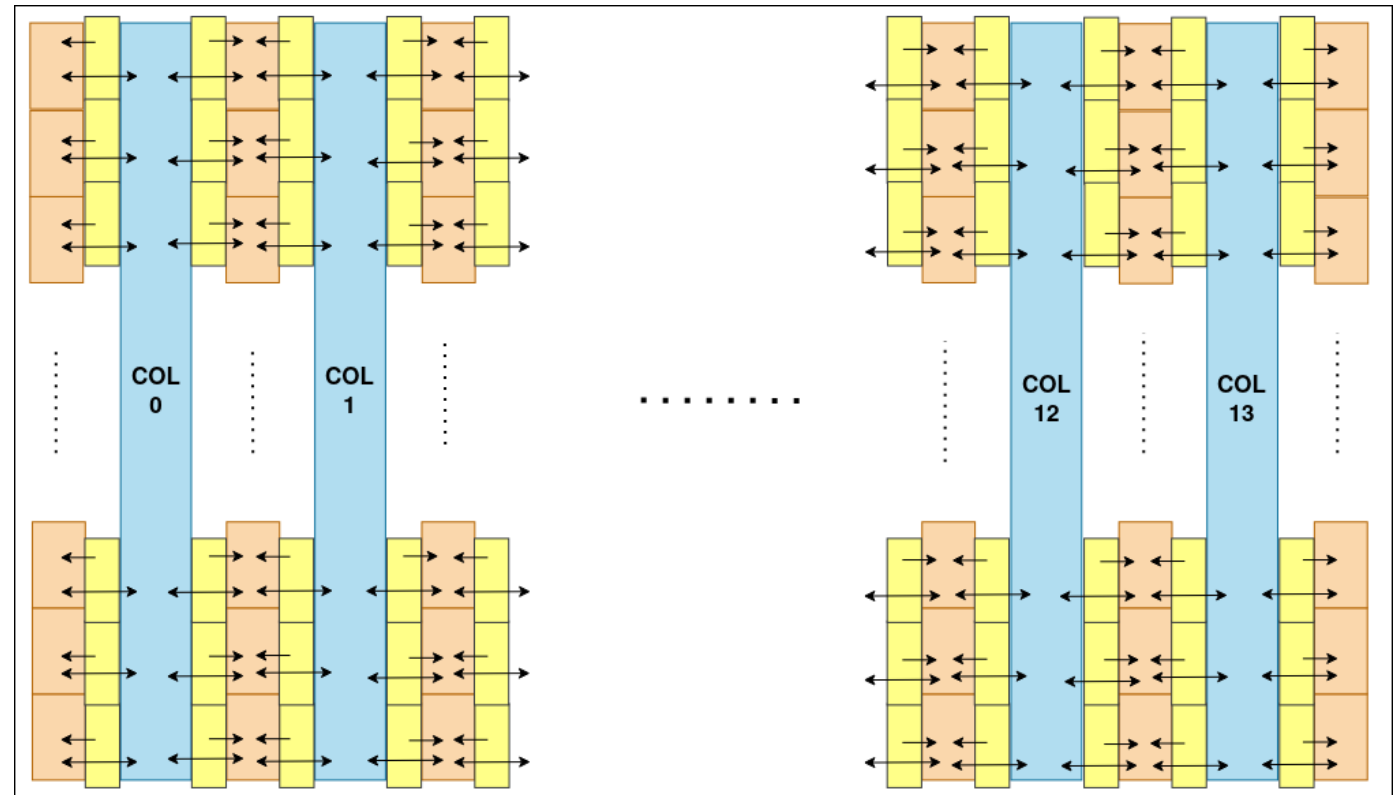
32x28 pixel matrix with a pixel pitch of 25x16 μm^2

The front-end is directly borrowed from CERN's DPTS

13 double columns of readout :

- 4 for 2-to-1
- 4 for 4-to-1
- 3 for 16-to-1 + 4-to-1
- 3 for 64-to-1

Enable a comparative evaluation of arbitration granularity and its impact on readout performance

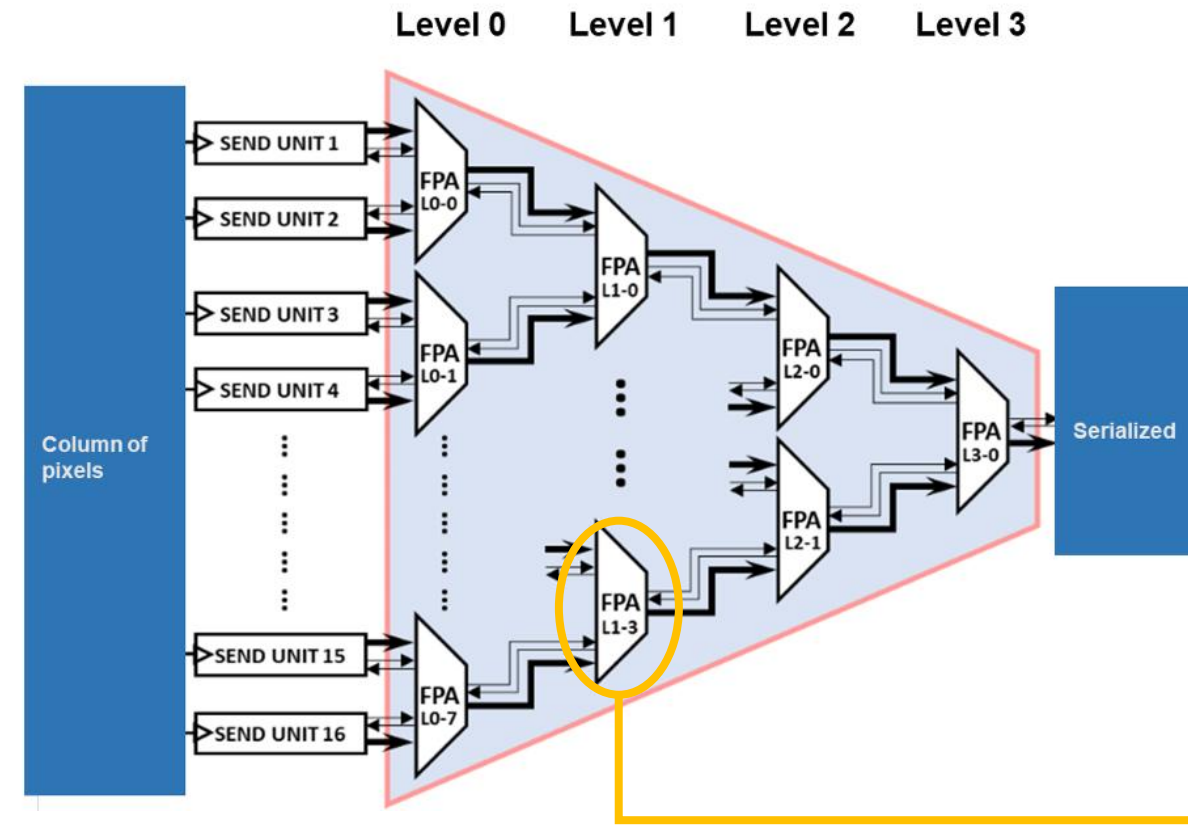


Digital In Pixel (DIP)

Pixel (PIX)

Column (COL)

Working principle of the asynchronous readout

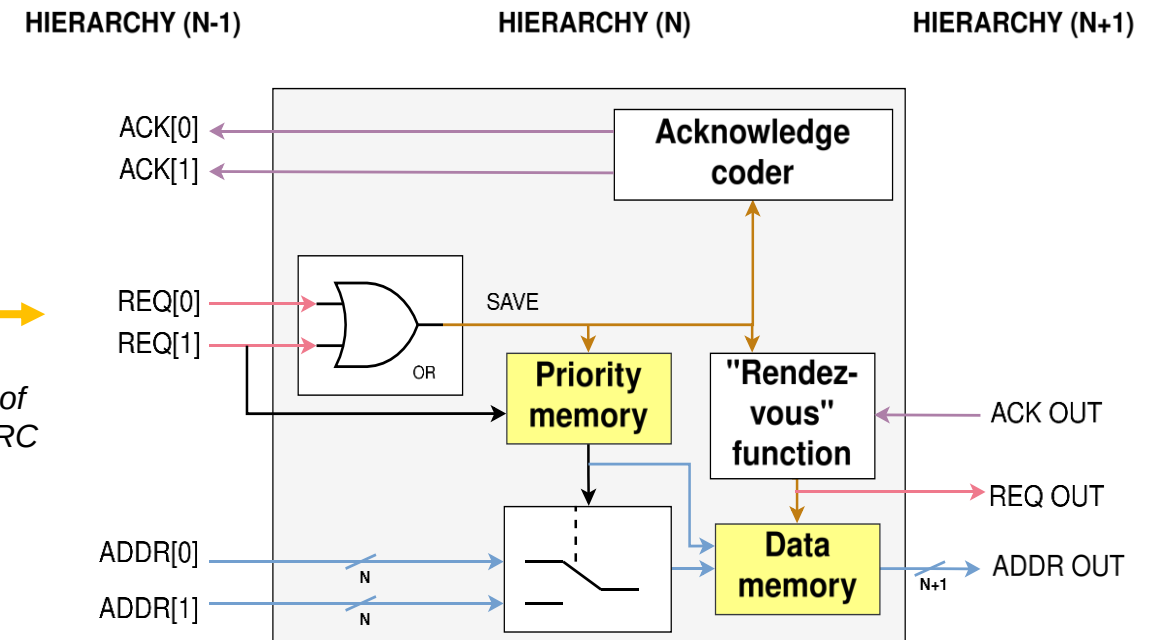


Architecture of the APA tree inside of readout columns in the matrix

APA architecture inside of readout columns of SPARC

Conflict-free, multi-speed compatible, event-driven

- **Detection** : OR gate (SAVE signal)
- **Arbitration** : priority memory, selects the winner
- **Selection** : MUX who routes the winner's address
- **Handshake** : 4-phase rendezvous (REQ↑ ACK↑ REQ↓ ACK↓)
- **Acknowledgement** : ACK coder to releases the served master



Sensor Architecture

FIFO + serializer

FIFO: buffers hit data (addr + timestamp) to absorb burst traffic
 Serializer: formats and sends data out on the output bus
 Output bus carries the complete hit word to the DAQ system

Fast OR selection	Timestamp (gray)	Address
1 bit	13 bits	10 bits

TABLE 5.1: Attribution of the 24 bits word in the FIFO.

Slow-control

Configuration interface (16 registers of 8 bits) for the whole chip
 Controls : pixel masking, threshold tuning, TDC calibration, test injection

TDC + VCO

VCO : generates a fine time base
 TDC : captures VCO phase at the moment of the hit
 Produces a digital timestamp per event
 Driven by Slow-Control for calibration
 Feeds timestamp directly into the FIFO alongside the pixel address

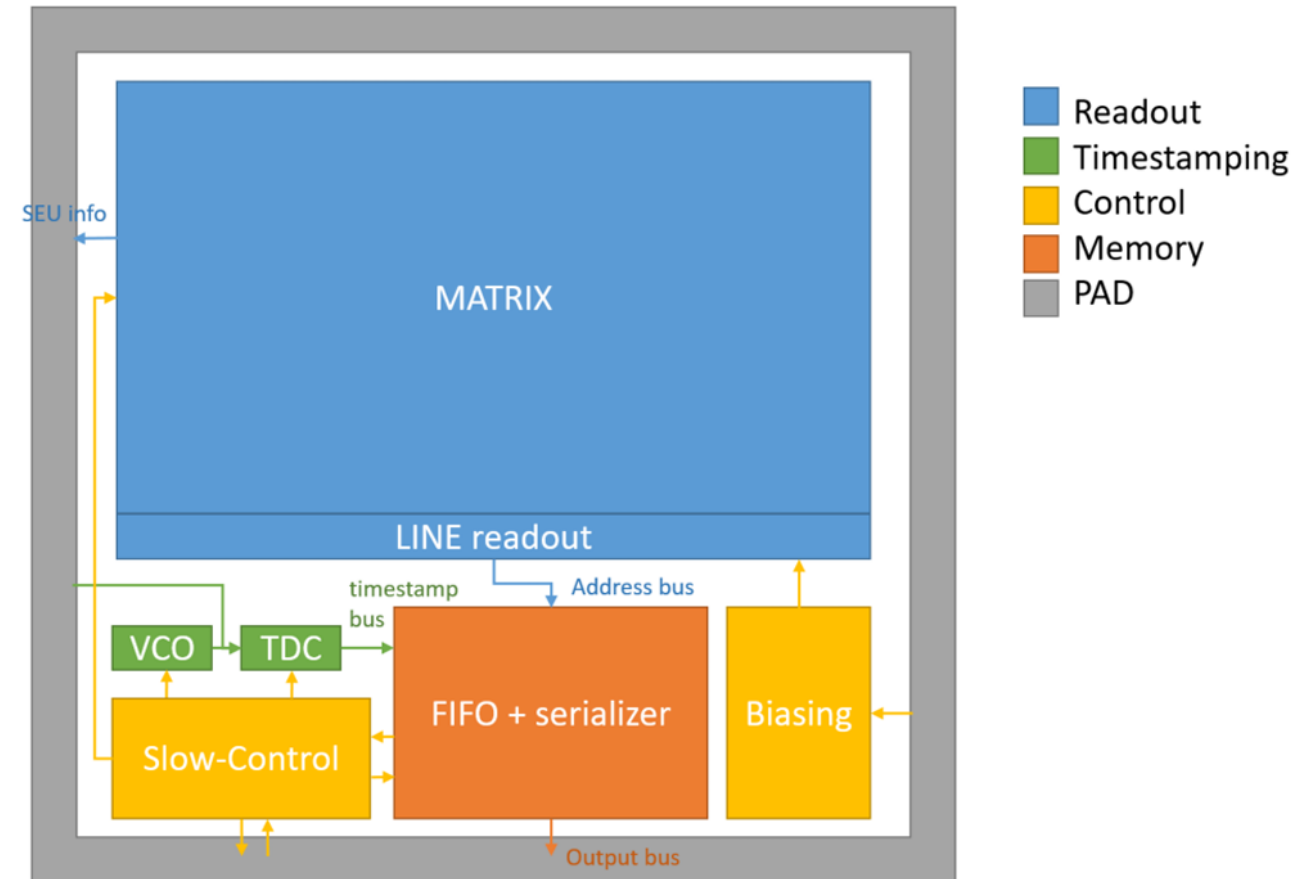


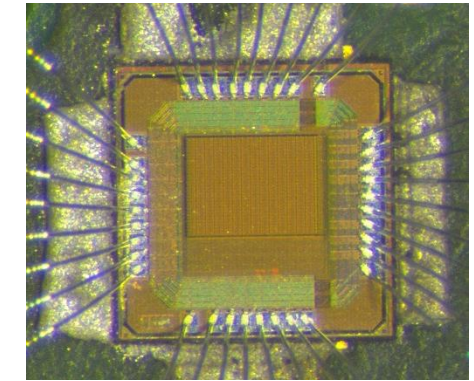
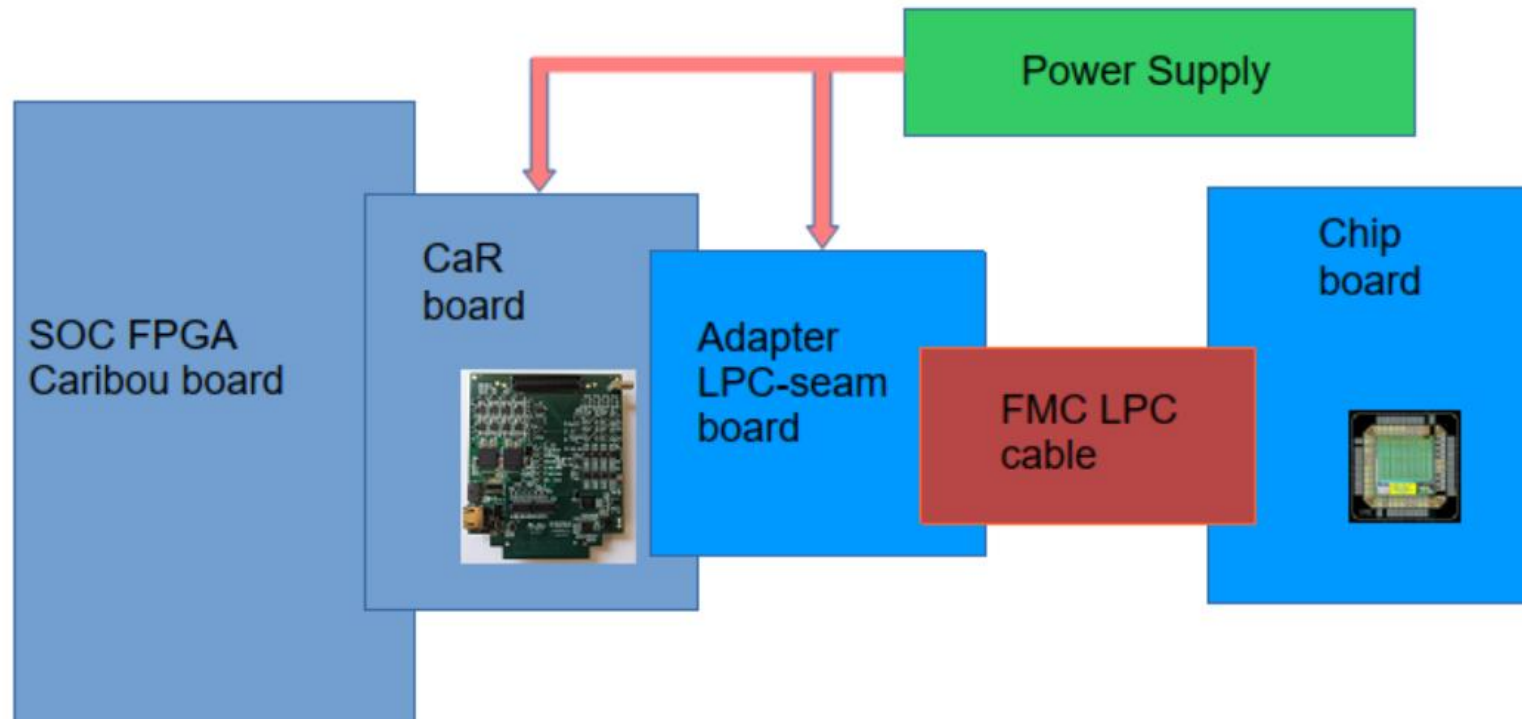
FIGURE 5.5: TOP view of the functional blocs of the SPARC sensor.

Biasing

Generates analog bias voltages for the pixel front-ends
 Configurable via Slow-Control registers

Test bench block diagram with FPGA-SOC as DAQ board

“CARIBOU only” test bench : It is the collaboration test bench for SPARC which will be distributed



SPARC

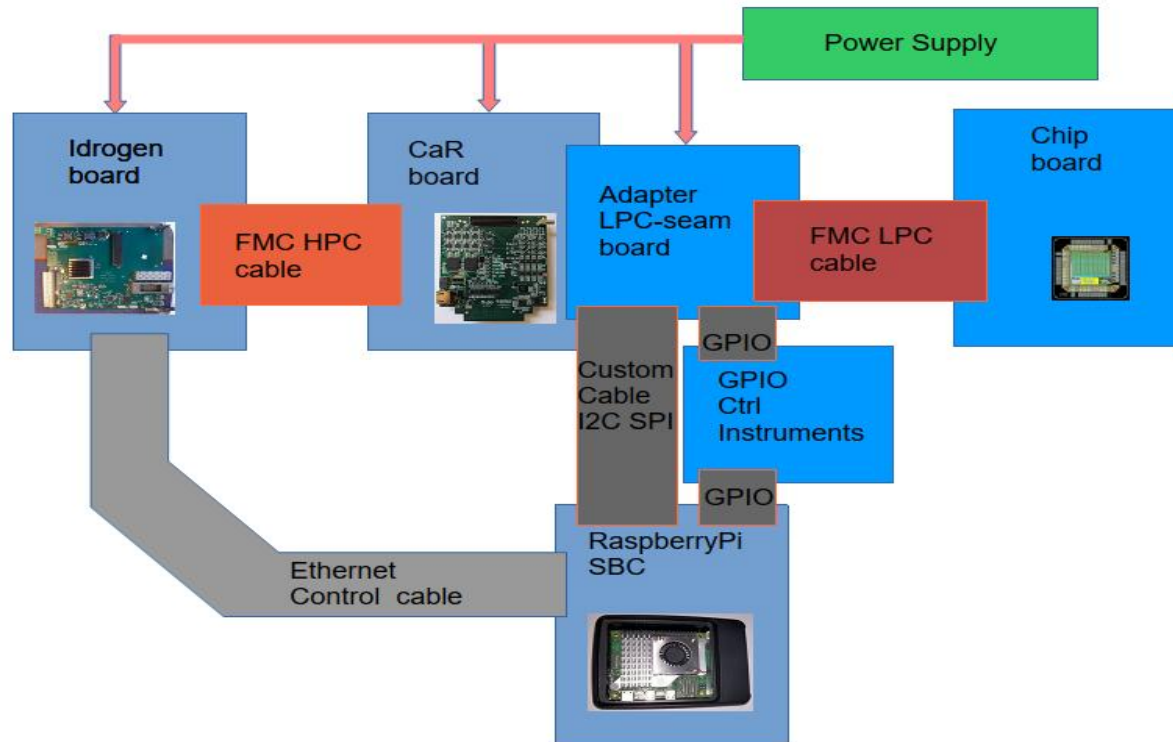
- Chip board / CaR board via FMC LPC cable
- Adapter board for LPC / seam 320 pins
- Caribou board
 - Slow control (I2C) config CaR
 - Slow control (SPI) config SPARC, Chip board
 - Acquiring data
- HW signal for SPARC testing (pulsing, etc) not presented on this slide

↑
Not ready yet !

There is two possible configurations:

- Plug the Chip Board directly onto the CaR Board.
- Insert a flat ribbon cable between them for greater flexibility but the adapter board is required.

Test bench block diagram with Idrogen (IJCLab IN2P3) as DAQ board



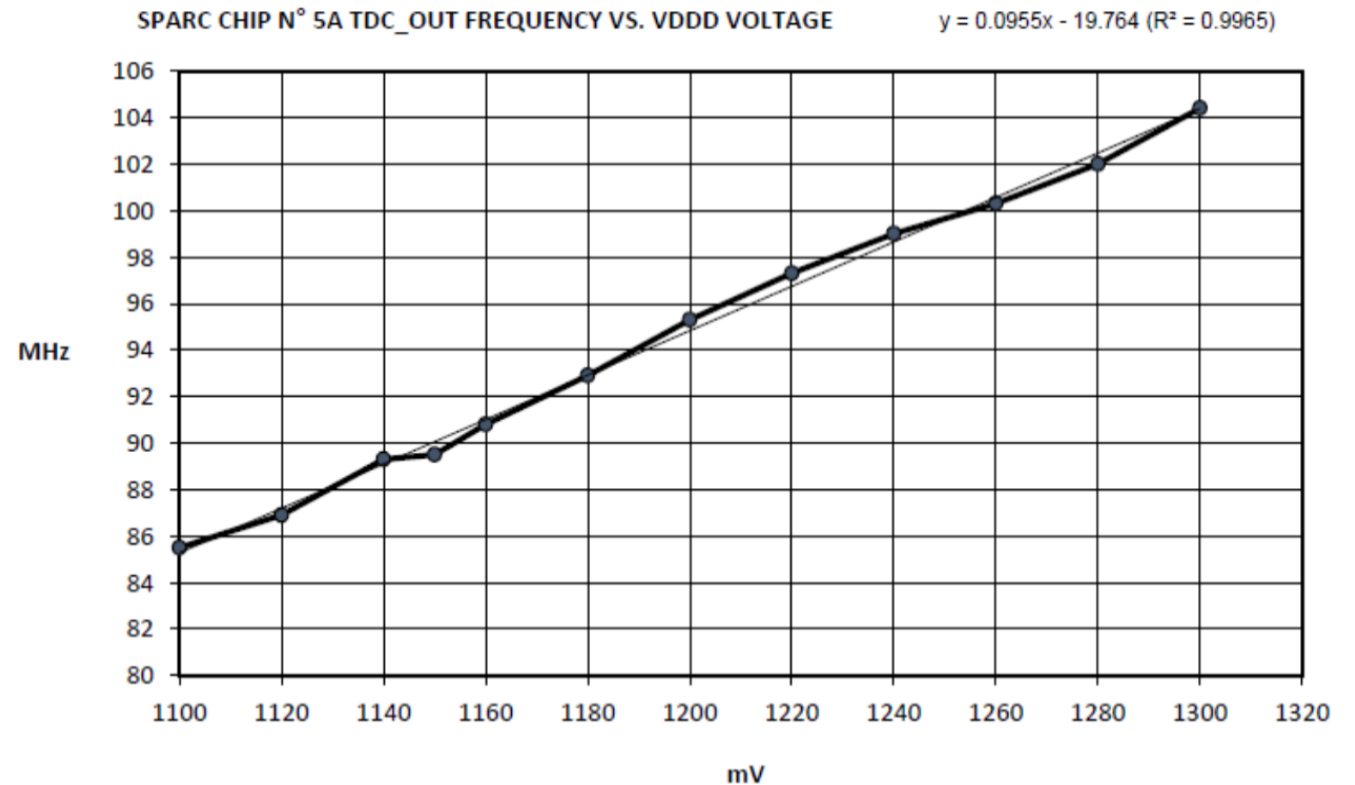
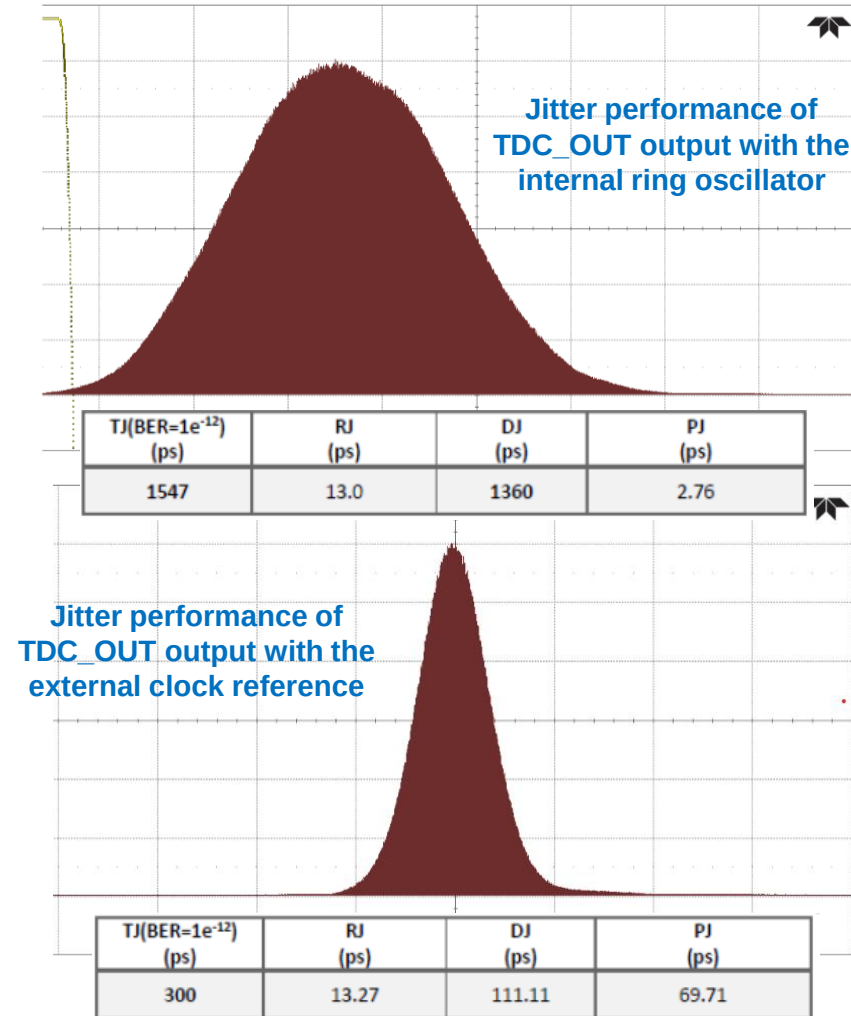
- Chip board / CaR board via FMC LPC cable
- Adapter board for LPC / seam 320 pins
- CaR to IDROGEN via FMC HPC cable
- DAQ Raspberry PI 5
 - Slow control (I2C) config CaR
 - Slow control (SPI) config SPARC, Chip board
 - Control IDROGEN (Ipbus ~ 20 MB/s)
- HW signal for SPARC testing (pulsing, etc) not presented on this slide

DAQ board Idrogen
IN2P3 - IJCLAB



Preliminary Measurement : Ring Oscillator Clock Jitter

- Measured conversion gain of the TDC_OUT related to power supply DVDD voltage: 96 KHz/mV
- Conversion gain KVDDD-to-ring_osc of the RING_OSC related to DVDD voltage: $8 * 96 \text{ KHz/mV} = 768 \text{ kHz/mV}$

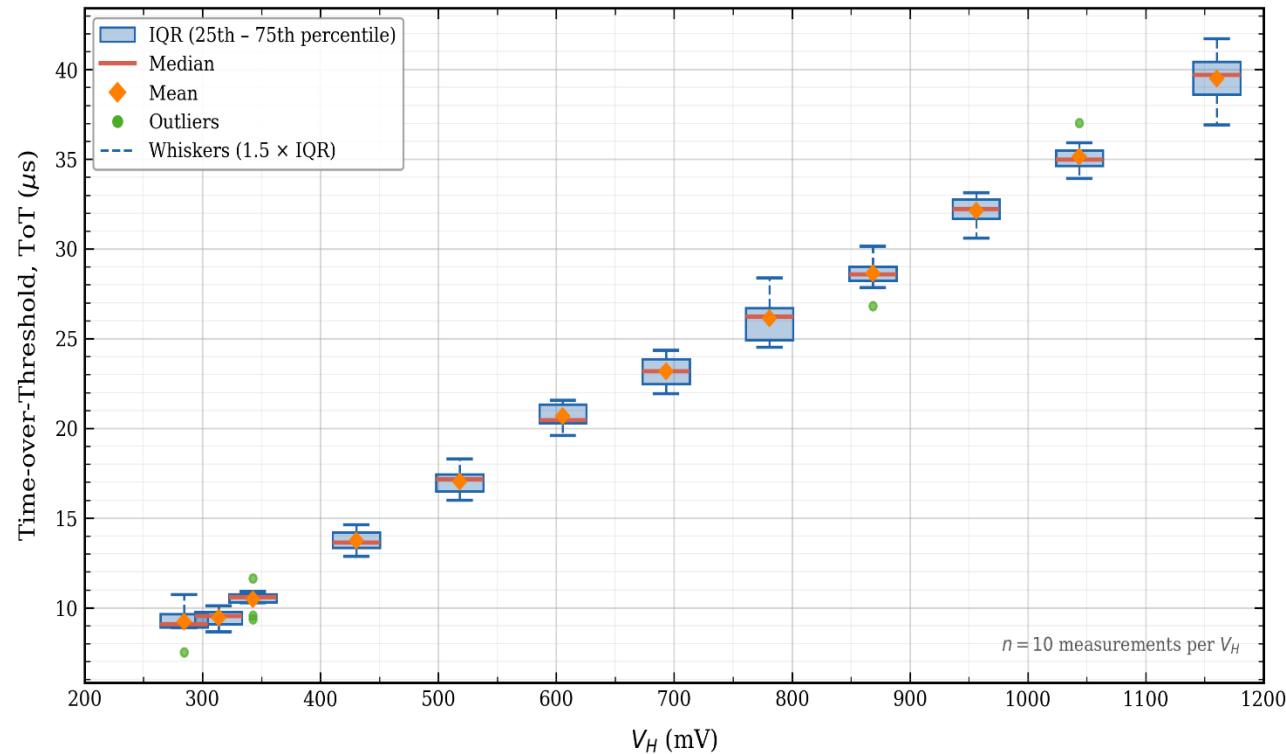


- Ring oscillator shows significantly larger jitter than external clock
- Internal oscillator is mainly intended for debug and tests, it is not designed to get a low jitter
- We will use external clock from Idrogen

Preliminary Measurement

First ToT measurements are consistent with simulations and confirm the functionality of the ToT mode.

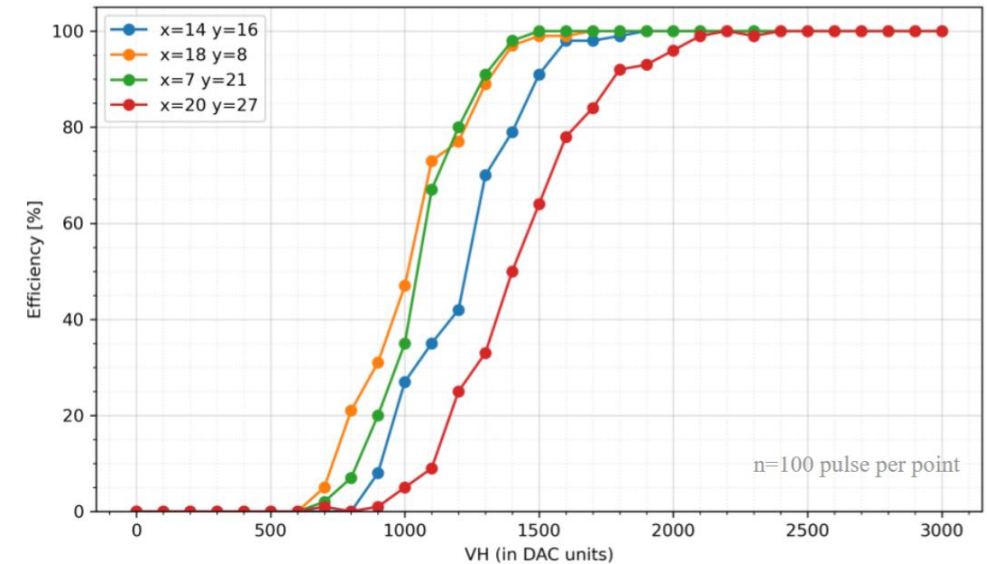
Distribution of ToT Measurements as a Function of V_H



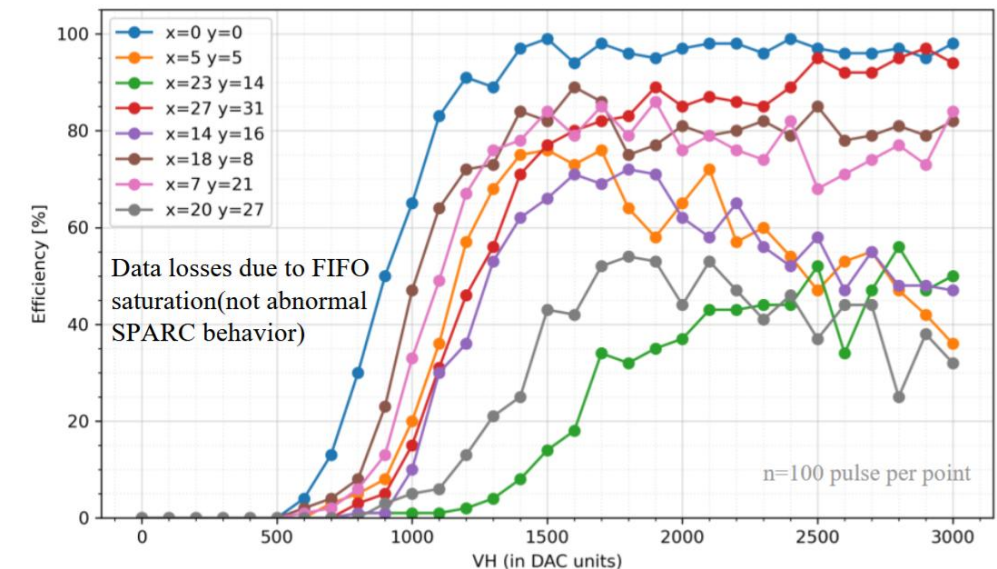
Simultaneous pulsing of 8 pixels $\rightarrow$ SPARC FIFO saturation (FIFO depth = 32) and data losses.

An upgrade of the acquisition software is ongoing to perform the scan using smaller groups of pixels (less than 8), avoiding FIFO saturation.

Preliminary SPARC S-Curves for 4 Pixels



Preliminary SPARC S-Curves for 8 Pixels





Thank you for your attention



Camille Fournier *on the behalf of SPARC core team*

Phd student, Institut Pluridisciplinaire Hubert Curien (IPHC)

Subatomic Research Department, C4PI team